

IGBT SIP MODULE

Short Circuit Rated UltraFast IGBT

Features

- Short Circuit Rated - 10 μ s @ 125°C, V_{GE} = 15V
- Fully isolated printed circuit board mount package
- Switching-loss rating includes all "tail" losses
- HEXFRED™ soft ultrafast diodes
- Optimized for high operating frequency (over 5kHz)

Product Summary

Output Current in a Typical 20 kHz Motor Drive

10 A_{RMS} with T_C = 90°C, T_J = 125°C, Supply Voltage 360Vdc,
Power Factor 0.8, Modulation Depth 80%.

Description

The IGBT technology is the key to International Rectifier's advanced line of IMS (Insulated Metal Substrate) Power Modules. These modules are more efficient than comparable bipolar transistor modules, while at the same time having the simpler gate-drive requirements of the familiar power MOSFET. This superior technology has now been coupled to a state of the art materials system that maximizes power throughput with low thermal resistance. This package is highly suited to power applications and where space is at a premium.

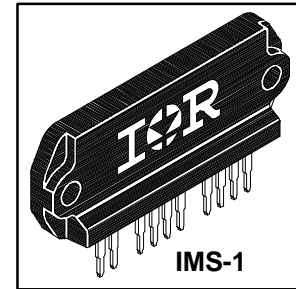
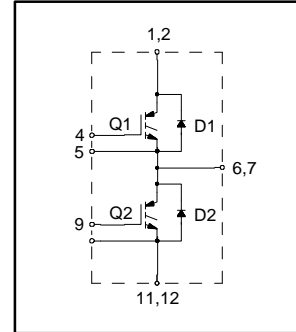
These new short circuit rated devices are especially suited for motor control and other totem-pole applications requiring short circuit withstand capability.

Absolute Maximum Ratings

	Parameter	Max.	Units
V _{CES}	Collector-to-Emitter Voltage	600	V
I _C @ T _C = 25°C	Continuous Collector Current, each IGBT	33	A
I _C @ T _C = 100°C	Continuous Collector Current, each IGBT	17	
I _{CM}	Pulsed Collector Current ①	100	
I _{LM}	Clamped Inductive Load Current ②	100	
I _F @ T _C = 100°C	Diode Continuous Forward Current	15	
I _{FM}	Diode Maximum Forward Current	100	
t _{sc}	Short Circuit Withstand Time	10	μ s
V _{GE}	Gate-to-Emitter Voltage	\pm 20	V
V _{ISOL}	Isolation Voltage, any terminal to case, 1 min.	2500	V _{RMS}
P _D @ T _C = 25°C	Maximum Power Dissipation, each IGBT	83	W
P _D @ T _C = 100°C	Maximum Power Dissipation, each IGBT	33	
T _J	Operating Junction and Storage Temperature Range	-40 to +150	°C
T _{STG}			
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting torque, 6-32 or M3 screw.	5-7 lbf•in (0.55 - 0.8 N•m)	

Thermal Resistance

	Parameter	Typ.	Max.	Units
R _{θJC} (IGBT)	Junction-to-Case, each IGBT, one IGBT in conduction	—	1.5	°C/W
R _{θJC} (DIODE)	Junction-to-Case, each diode, one diode in conduction	—	2.0	
R _{θCS} (MODULE)	Case-to-Sink, flat, greased surface	0.1	—	
Wt	Weight of module	20 (0.7)	—	g (oz)



CPU165MK



Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage ③	600	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temp. Coeff. of Breakdown Voltage	—	0.60	—	V/°C	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	2.1	2.7	V	$I_C = 30A, V_{GE} = 15V$
		—	2.6	—		$I_C = 52A$
		—	2.3	—		$I_C = 30A, T_J = 150^\circ\text{C}$
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	5.5		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temp. Coeff. of Threshold Voltage	—	-14	—	mV/°C	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ④	9.8	17	—	S	$V_{CE} = 100V, I_C = 30A$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{GE} = 0V, V_{CE} = 600V$
		—	—	6500		$V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	1.3	1.7	V	$I_C = 25A$
		—	1.2	1.5		$I_C = 25A, T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 500	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
Q_g	Total Gate Charge (turn-on)	—	120	200	nC	$I_C = 30A$ $V_{CC} = 400V$	
Q_{ge}	Gate - Emitter Charge (turn-on)	—	27	42			
Q_{gc}	Gate - Collector Charge (turn-on)	—	44	73			
$t_{d(on)}$	Turn-On Delay Time	—	74	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 30A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 5.0\Omega$ Energy losses include "tail" and diode reverse recovery.	
t_r	Rise Time	—	100	—			
$t_{d(off)}$	Turn-Off Delay Time	—	260	460			
t_f	Fall Time	—	190	290			
E_{on}	Turn-On Switching Loss	—	1.9	—			
E_{off}	Turn-Off Switching Loss	—	2.6	—	mJ		
E_{ts}	Total Switching Loss	—	4.5	7.0			
t_{sc}	Short Circuit Withstand Time	10	—	—	μs	$V_{CC} = 360V, T_J = 125^\circ\text{C}$ $V_{GE} = 15V, R_G = 5.0\Omega, V_{CPK} < 500V$	
$t_{d(on)}$	Turn-On Delay Time	—	77	—	ns	$T_J = 150^\circ\text{C}$, $I_C = 30A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 5.0\Omega$ Energy losses include "tail" and diode reverse recovery.	
t_r	Rise Time	—	100	—			
$t_{d(off)}$	Turn-Off Delay Time	—	530	—			
t_f	Fall Time	—	360	—			
E_{ts}	Total Switching Loss	—	7.3	—	mJ		
C_{ies}	Input Capacitance	—	2900	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ $f = 1.0MHz$	
C_{oes}	Output Capacitance	—	220	—			
C_{res}	Reverse Transfer Capacitance	—	30	—			
t_{rr}	Diode Reverse Recovery Time	—	50	75	ns	$T_J = 25^\circ\text{C}$	$I_F = 25A$ $V_R = 200V$ $di/dt = 200A/\mu s$
		—	105	160		$T_J = 125^\circ\text{C}$	
I_{rr}	Diode Peak Reverse Recovery Current	—	4.5	10	A	$T_J = 25^\circ\text{C}$	
		—	8.0	15		$T_J = 125^\circ\text{C}$	
Q_{rr}	Diode Reverse Recovery Charge	—	112	375	nC	$T_J = 25^\circ\text{C}$	
		—	420	1200		$T_J = 125^\circ\text{C}$	
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery During t_b	—	250	—	A/ μs	$T_J = 25^\circ\text{C}$	
		—	160	—		$T_J = 125^\circ\text{C}$	

Notes: ① Repetitive rating; $V_{GE}=20V$, pulse width limited by max. junction temperature.

② $V_{CC}=80\%(V_{CES}), V_{GE}=20V, L=10\mu H, R_G=5.0\Omega$.

④ Pulse width 5.0 μs , single shot.

③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.

Refer to Section D - page D-13 for Package Outline 4 - IMS-1 Package (10 pins)